

Welcome to E-XFL.COM

#### What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

#### Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

E·XF

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I <sup>2</sup> C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	12
Program Memory Size	3.5КВ (2К х 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	14-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	14-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1823-e-st

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

## 3.2.2 SPECIAL FUNCTION REGISTER

The Special Function Registers are registers used by the application to control the desired operation of peripheral functions in the device. The registers associated with the operation of the peripherals are described in the appropriate peripheral chapter of this data sheet.

## 3.2.3 GENERAL PURPOSE RAM

There are up to 80 bytes of GPR in each data memory bank.

## 3.2.3.1 Linear Access to GPR

The general purpose RAM can be accessed in a non-banked method via the FSRs. This can simplify access to large memory structures. See **Section 3.5.2** "**Linear Data Memory**" for more information.

## 3.2.4 COMMON RAM

There are 16 bytes of common RAM accessible from all banks.

## FIGURE 3-2: BANKED MEMORY PARTITIONING



## 3.2.5 DEVICE MEMORY MAPS

The memory maps for the device family are as shown in Table 3-2.

## TABLE 3-2: MEMORY MAP TABLES

Device	Banks	Table No.
	0-7	Table 3-3
	8-15	Table 3-4
PIC12(L)F1822/16(L)F1823	16-23	Table 3-5
	24-31	Table 3-6
	31	Table 3-7



## 3.4.2 OVERFLOW/UNDERFLOW RESET

If the STVREN bit in Configuration Word 2 is programmed to '1', the device will be reset if the stack is PUSHed beyond the sixteenth level or POPed beyond the first level, setting the appropriate bits (STKOVF or STKUNF, respectively) in the PCON register.

## 3.5 Indirect Addressing

The INDFn registers are not physical registers. Any instruction that accesses an INDFn register actually accesses the register at the address specified by the File Select Registers (FSR). If the FSRn address specifies one of the two INDFn registers, the read will return '0' and the write will not occur (though Status bits may be affected). The FSRn register value is created by the pair FSRnH and FSRnL.

The FSR registers form a 16-bit address that allows an addressing space with 65536 locations. These locations are divided into three memory regions:

- · Traditional Data Memory
- Linear Data Memory
- Program Flash Memory

## 5.2.1.5 TIMER1 Oscillator

The Timer1 Oscillator is a separate crystal oscillator that is associated with the Timer1 peripheral. It is optimized for timekeeping operations with a 32.768 kHz crystal connected between the T1OSO and T1OSI device pins.

The Timer1 Oscillator can be used as an alternate system clock source and can be selected during run-time using clock switching. Refer to **Section 5.3** "**Clock Switching**" for more information.

### FIGURE 5-5: QUARTZ CRYSTAL OPERATION (TIMER1 OSCILLATOR)



- Note 1: Quartz crystal characteristics vary according to type, package and manufacturer. The user should consult the manufacturer data sheets for specifications and recommended application.
  - 2: Always verify oscillator performance over the VDD and temperature range that is expected for the application.
  - **3:** For oscillator design assistance, reference the following Microchip Applications Notes:
    - AN826, "Crystal Oscillator Basics and Crystal Selection for rfPIC<sup>®</sup> and PIC<sup>®</sup> Devices" (DS00826)
    - AN849, "Basic PIC<sup>®</sup> Oscillator Design" (DS00849)
    - AN943, "Practical PIC<sup>®</sup> Oscillator Analysis and Design" (DS00943)
    - AN949, "Making Your Oscillator Work" (DS00949)
    - TB097, "Interfacing a Micro Crystal MS1V-T1K 32.768 kHz Tuning Fork Crystal to a PIC16F690/SS" (DS91097)
    - AN1288, "Design Practices for Low-Power External Oscillators" (DS01288)

## 5.2.1.6 External RC Mode

The external Resistor-Capacitor (RC) modes support the use of an external RC circuit. This allows the designer maximum flexibility in frequency choice while keeping costs to a minimum when clock accuracy is not required.

The RC circuit connects to OSC1. OSC2/CLKOUT is available for general purpose I/O or CLKOUT. The function of the OSC2/CLKOUT pin is determined by the state of the CLKOUTEN bit in Configuration Word 1.

Figure 5-6 shows the external RC mode connections.





The RC oscillator frequency is a function of the supply voltage, the resistor (REXT) and capacitor (CEXT) values and the operating temperature. Other factors affecting the oscillator frequency are:

- threshold voltage variation
- component tolerances
- · packaging variations in capacitance

The user also needs to take into account variation due to tolerance of external RC components used.

## 5.2.2 INTERNAL CLOCK SOURCES

The device may be configured to use the internal oscillator block as the system clock by performing one of the following actions:

- Program the FOSC<2:0> bits in Configuration Word 1 to select the INTOSC clock source, which will be used as the default system clock upon a device Reset.
- Write the SCS<1:0> bits in the OSCCON register to switch the system clock source to the internal oscillator during run-time. See **Section 5.3 "Clock Switching"**for more information.

In **INTOSC** mode, OSC1/CLKIN is available for general purpose I/O. OSC2/CLKOUT is available for general purpose I/O or CLKOUT.

The function of the <u>OSC2/CLKOUT</u> pin is determined by the state of the <u>CLKOUTEN</u> bit in Configuration Word 1.

The internal oscillator block has two independent oscillators and a dedicated Phase-Locked Loop, HFPLL that can produce one of three internal system clock sources.

- 1. The **HFINTOSC** (High-Frequency Internal Oscillator) is factory calibrated and operates at 16 MHz. The HFINTOSC source is generated from the 500 kHz MFINTOSC source and the dedicated Phase-Locked Loop, HFPLL. The frequency of the HFINTOSC can be user-adjusted via software using the OSCTUNE register (Register 5-3).
- The MFINTOSC (Medium-Frequency Internal Oscillator) is factory calibrated and operates at 500 kHz. The frequency of the MFINTOSC can be user-adjusted via software using the OSCTUNE register (Register 5-3).
- 3. The **LFINTOSC** (Low-Frequency Internal Oscillator) is uncalibrated and operates at 31 kHz.

## 5.2.2.1 HFINTOSC

The High-Frequency Internal Oscillator (HFINTOSC) is a factory calibrated 16 MHz internal clock source. The frequency of the HFINTOSC can be altered via software using the OSCTUNE register (Register 5-3).

The output of the HFINTOSC connects to a postscaler and multiplexer (see Figure 5-1). One of nine frequencies derived from the HFINTOSC can be selected via software using the IRCF<3:0> bits of the OSCCON register. See **Section 5.2.2.7** "Internal Oscillator Clock Switch Timing" for more information.

The HFINTOSC is enabled by:

- Configure the IRCF<3:0> bits of the OSCCON register for the desired HF frequency, and
- FOSC<2:0> = 100, or
- Set the System Clock Source (SCS) bits of the OSCCON register to '1x'.

The High Frequency Internal Oscillator Ready bit (HFIOFR) of the OSCSTAT register indicates when the HFINTOSC is running and can be utilized.

The High Frequency Internal Oscillator Status Locked bit (HFIOFL) of the OSCSTAT register indicates when the HFINTOSC is running within 2% of its final value.

The High Frequency Internal Oscillator Status Stable bit (HFIOFS) of the OSCSTAT register indicates when the HFINTOSC is running within 0.5% of its final value.

## 5.2.2.2 MFINTOSC

The Medium-Frequency Internal Oscillator (MFINTOSC) is a factory calibrated 500 kHz internal clock source. The frequency of the MFINTOSC can be altered via software using the OSCTUNE register (Register 5-3).

The output of the MFINTOSC connects to a postscaler and multiplexer (see Figure 5-1). One of nine frequencies derived from the MFINTOSC can be selected via software using the IRCF<3:0> bits of the OSCCON register. See **Section 5.2.2.7** "Internal Oscillator Clock Switch Timing" for more information.

The MFINTOSC is enabled by:

- Configure the IRCF<3:0> bits of the OSCCON register for the desired HF frequency, and
- FOSC<2:0> = 100, or
- Set the System Clock Source (SCS) bits of the OSCCON register to '1x'

The Medium Frequency Internal Oscillator Ready bit (MFIOFR) of the OSCSTAT register indicates when the MFINTOSC is running and can be utilized.

## TABLE 6-1: SUMMARY OF REGISTERS ASSOCIATED WITH REFERENCE CLOCK SOURCES

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page	
CLKRCON	CLKREN	CLKROE	CLKRSLR	CLKRDC1	CLKRDC0	CLKRDIV2	CLKRDIV1	CLKRDIV0	69	
Legend:	<b>Learned</b> : $-$ = unimplemented locations read as $(0)$ . Shaded cells are not used by reference clock sources									

**Legend:** — = unimplemented locations read as '0'. Shaded cells are not used by reference clock sources.

## TABLE 6-2: SUMMARY OF CONFIGURATION WORD WITH REFERENCE CLOCK SOURCES

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
	13:8	_	_	FCMEN	IESO	CLKOUTEN	BOREN1	BOREN0	CPD	40
CONFIGT	7:0	CP	MCLRE	PWRTE	WDTE1	WDTE0	FOSC2	FOSC1	FOSC0	40

Legend: — = unimplemented locations read as '0'. Shaded cells are not used by reference clock sources.

## 11.6 Write Verify

Depending on the application, good programming practice may dictate that the value written to the data EEPROM or program memory should be verified (see Example 11-6) to the desired value to be written. Example 11-6 shows how to verify a write to EEPROM.

## EXAMPLE 11-6: EEPROM WRITE VERIFY

BANKSEL	EEDATL	;
MOVF	EEDATL, W	;EEDATL not changed
		;from previous write
BSF	EECON1, RE	;YES, Read the
		;value written
XORWF	EEDATL, W	;
BTFSS	STATUS, Z	;Is data the same
GOTO	WRITE_ERR	;No, handle error
:		;Yes, continue

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELA	—	_	—	ANSA4	—	ANSA2	ANSA1	ANSA0	118
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	86
IOCAF	—	—	IOCAF5	IOCAF4	IOCAF3	IOCAF2	IOCAF1	IOCAF0	125
IOCAN	_	_	IOCAN5	IOCAN4	IOCAN3	IOCAN2	IOCAN1	IOCAN0	125
IOCAP	_	_	IOCAP5	IOCAP4	IOCAP3	IOCAP2	IOCAP1	IOCAP0	125
TRISA			TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	117

## TABLE 13-1: SUMMARY OF REGISTERS ASSOCIATED WITH INTERRUPT-ON-CHANGE

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by interrupt-on-change.

## 16.2.7 ADC REGISTER DEFINITIONS

The following registers are used to control the operation of the ADC.

### REGISTER 16-1: ADCON0: A/D CONTROL REGISTER 0

U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
			CHS<4:0>			GO/DONE	ADON
bit 7							bit 0
r							
Legend:							
R = Readab	ole bit	W = Writable	bit	U = Unimpler	nented bit, rea	d as '0'	
u = Bit is un	changed	x = Bit is unkr	nown	-n/n = Value a	at POR and BO	OR/Value at all o	other Resets
'1' = Bit is s	et	'0' = Bit is cle	ared				
bit 7	Unimpleme	nted: Read as '	0'				
bit 6-2	CHS<4:0>: /	Analog Channel	Select bits				
	00000 <b>= AN</b>	0					
	00001 = AN	1					
	00010 = AN	2					
	00011 - AN	3 4(1)					
	00100 = AN	- 5 <sup>(1)</sup>					
	00110 = AN	- 6(1)					
	00111 <b>= AN</b>	7 <sup>(1)</sup>					
	01001 <b>= Res</b>	served. No char	nnel connected	d.			
	•						
	•						
	11100 <b>= Re</b> s	served. No char	nnel connecte	d.			
	11101 = Ten	nperature Indica	ator <sup>(4)</sup>				
	11110 <b>= DA</b>	C output <sup>(2)</sup>					
	11111 <b>= FV</b> F	R (Fixed Voltage	e Reference) E	Buffer 1 Output <sup>(</sup>	3)		
bit 1	GO/DONE: A	A/D Conversion	Status bit				
	1 = A/D conv	version cycle in	progress. Set	ting this bit start	s an A/D conv	ersion cycle.	
	This bit is	s automatically	cleared by har	dware when the	e A/D convers	ion has complet	ed.
	0 = A/D conv	ersion complet	ed/not in prog	ress			
bit 0	ADON: ADC	Enable bit					
	$\perp = ADC$ is e	inabled lisabled and co		orating current			
			isumes no op	erating current			
Note 1: F	PIC16(L)F1823 o	nly. For PIC12(	L)F1822 it is "l	Reserved. No c	hannel conneo	cted".	
2: 8	See Section 17.0	) "Digital-to-Ar	alog Convert	ter (DAC) Modu	u <b>le</b> " for more i	nformation.	
3: 5	See Section 14.0	) "Fixed Voltag	e Reference	(FVR)" for more	e information.		

4: See Section 15.0 "Temperature Indicator Module" for more information.

## 20.0 TIMER0 MODULE

The Timer0 module is an 8-bit timer/counter with the following features:

- 8-bit timer/counter register (TMR0)
- 8-bit prescaler (independent of Watchdog Timer)
- Programmable internal or external clock source
- Programmable external clock edge selection
- Interrupt on overflow
- TMR0 can be used to gate Timer1

Figure 20-1 is a block diagram of the Timer0 module.

## 20.1 Timer0 Operation

The Timer0 module can be used as either an 8-bit timer or an 8-bit counter.

## 20.1.1 8-BIT TIMER MODE

The Timer0 module will increment every instruction cycle, if used without a prescaler. 8-bit Timer mode is selected by clearing the TMR0CS bit of the OPTION register.

When TMR0 is written, the increment is inhibited for two instruction cycles immediately following the write.

**Note:** The value written to the TMR0 register can be adjusted, in order to account for the two instruction cycle delay when TMR0 is written.

## 20.1.2 8-BIT COUNTER MODE

In 8-Bit Counter mode, the Timer0 module will increment on every rising or falling edge of the T0CKI pin or the Capacitive Sensing Oscillator (CPSCLK) signal.

8-Bit Counter mode using the T0CKI pin is selected by setting the TMR0CS bit in the OPTION register to '1' and resetting the T0XCS bit in the CPSCON0 register to '0'.

8-Bit Counter mode using the Capacitive Sensing Oscillator (CPSCLK) signal is selected by setting the TMR0CS bit in the OPTION register to '1' and setting the T0XCS bit in the CPSCON0 register to '1'.

The rising or falling transition of the incrementing edge for either input source is determined by the TMR0SE bit in the OPTION register.



## FIGURE 20-1: BLOCK DIAGRAM OF THE TIMER0

FIGURE 21-6:	TIMER1 GATE SINGLI	E-PULSE AND TOGGLE COMBINED MODE
TMR1GE		
T1GPOL		
T1GSPM		
T1GTM		
T1GG <u>O/</u> DONE	✓ Set by software Counting enabled	on
T1G_IN		
Т1СКІ		
T1GVAL		
Timer1	Ν	N + 1 N + 2 N + 3 N + 4
TMR1GIF	<ul> <li>Cleared by software</li> </ul>	Set by hardware on Cleared by falling edge of T1GVAL —

## 

R/W-x/u	U-0	U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
MDMSODIS	—	_	—		MDMS	6<3:0>	
bit 7							bit 0
Legend:							
R = Readable	bit	W = Writable	bit	U = Unimplen	nented bit, read	l as '0'	
u = Bit is uncha	anged	x = Bit is unkr	iown	-n/n = Value a	t POR and BO	R/Value at all o	other Resets
'1' = Bit is set	0	'0' = Bit is clea	ared				
		2.1.0 0.00					
bit 7	MDMSODIS:	Modulation So	urce Output I	Disable bit			
	1 = Output si	anal driving the	e peripheral c	output pin (selec	ted by MDMS<	3:0>) is disable	ed
	0 = Output si	gnal driving the	e peripheral c	output pin (selec	ted by MDMS<	3:0>) is enable	ed
bit 6-4	Unimplemen	ted: Read as '	D'				
bit 3-0	MDMS<3:0>	Modulation Sou	urce Selectio	n bits			
	1111 = Rese	erved. No char	nnel connecte	ed.			
	1110 = Rese	erved. No char	nnel connecte	ed.			
	1101 = Rese	erved. No char	nnel connecte	ed.			
	1100 = Rese	erved. No char	nnel connecte	ed.			
	1011 = Rese	erved. No char	nnel connecte	ed.			
	1010 = EUS	ART TX output	t				
	1001 = Rese	erved. No chan	nel selected.				
	1000 = MSS	P1 SDO1 outp	ut				
	0111 = Com	parator 2 outpu	t (PIC16(L)F	1823 only. PIC12	2(L)F1822; Rese	erved, no chann	el connected.)
	0110 = Com	parator 1 outpu	t				
	0101 = Rese	erved. No char	nnel connecte	ed.			
	0100 = Rese	erved. No char	nnel connecte	ed.			
	0011 = Rese	erved. No char	nnel connecte	ed.			
	0010 = CCP	1 output (PWN	1 Output mod	le only)			
	0001 = MDN	/IN port pin					
	0000 = MDE	BIT bit of MDCC	DN register is	modulation sou	irce		

## REGISTER 23-2: MDSRC: MODULATION SOURCE CONTROL REGISTER

Note 1: Narrowed carrier pulse widths or spurs may occur in the signal stream if the carrier is not synchronized.

## 24.3 PWM Overview

Pulse-Width Modulation (PWM) is a scheme that provides power to a load by switching quickly between fully on and fully off states. The PWM signal resembles a square wave where the high portion of the signal is considered the on state and the low portion of the signal is considered the off state. The high portion, also known as the pulse width, can vary in time and is defined in steps. A larger number of steps applied, which lengthens the pulse width, also supplies more power to the load. Lowering the number of steps applied, which shortens the pulse width, supplies less power. The PWM period is defined as the duration of one complete cycle or the total amount of on and off time combined.

PWM resolution defines the maximum number of steps that can be present in a single PWM period. A higher resolution allows for more precise control of the pulse width time and in turn the power that is applied to the load.

The term duty cycle describes the proportion of the on time to the off time and is expressed in percentages, where 0% is fully off and 100% is fully on. A lower duty cycle corresponds to less power applied and a higher duty cycle corresponds to more power applied.

Figure 24-3 shows a typical waveform of the PWM signal.

## 24.3.1 STANDARD PWM OPERATION

The standard PWM mode generates a Pulse-Width modulation (PWM) signal on the CCP1 pin with up to 10 bits of resolution. The period, duty cycle, and resolution are controlled by the following registers:

- · PR2 registers
- T2CON registers
- CCPR1L registers
- CCP1CON registers

Figure 24-4 shows a simplified block diagram of PWM operation.

Note 1:	The	corresponding	TRIS	bit	must	be
	cleare	ed to enable the	PWM	out	out on	the
	CCP	1 pin.				

**2:** Clearing the CCP1CON register will relinquish control of the CCP1 pin.

## FIGURE 24-3: CCP1 PWM OUTPUT SIGNAL





#### SIMPLIFIED PWM BLOCK DIAGRAM



## 24.4.8 ALTERNATE PIN LOCATIONS

This module incorporates I/O pins that can be moved to other locations with the use of the alternate pin function register, APFCON. To determine which pins can be moved and what their default locations are upon a reset, see **Section 12.1 "Alternate Pin Function"** for more information.

TABLE 24-10: SUMMART OF REGISTERS ASSOCIATED WITH ENHANCED PW	TABLE 24-10:	SUMMARY OF REGISTERS ASSOCIATED WITH ENHANCED PWM
---	--------------	---

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page	
APFCON	RXDTSEL	SDOSEL	SSSEL	—	T1GSEL	TXCKSEL	P1BSEL <sup>(2)</sup>	CCP1SEL <sup>(2)</sup>	114	
CCP1CON	P1M•	<1:0> DC1B<1:0>				213				
CCP1AS	CCP1ASE	CCP1AS<2:0>			PSS1A	.C<1:0>	PSS1BD<1:0>		214	
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	86	
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	87	
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	89	
PR2	Timer2 Period	Register								
PSTR1CON	—	—	—	STR1SYNC	STR1D <sup>(1)</sup>	STR1C <sup>(1)</sup>	STR1B	STR1A	216	
PWM1CON	P1RSEN				P1DC<6:0>				215	
T2CON	—		T2OUTI	PS<3:0>		TMR2ON	T2CKP	'S<:0>1	178	
TMR2	Timer2 Modu	r2 Module Register						176*		
TRISA	_	_	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	117	
TRISC <sup>(1)</sup>	—	_	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	121	

Legend: — = Unimplemented location, read as '0'. Shaded cells are not used by the PWM.

\* Page provides register information.

Note 1: PIC16(L)F1823 only.

2: PIC12(L)F1822 only.

When one device is transmitting a logical one, or letting the line float, and a second device is transmitting a logical zero, or holding the line low, the first device can detect that the line is not a logical one. This detection, when used on the SCL line, is called clock stretching. Clock stretching gives slave devices a mechanism to control the flow of data. When this detection is used on the SDA line, it is called arbitration. Arbitration ensures that there is only one master device communicating at any single time.

## 25.3.1 CLOCK STRETCHING

When a slave device has not completed processing data, it can delay the transfer of more data through the process of Clock Stretching. An addressed slave device may hold the SCL clock line low after receiving or sending a bit, indicating that it is not yet ready to continue. The master that is communicating with the slave will attempt to raise the SCL line in order to transfer the next bit, but will detect that the clock line has not yet been released. Because the SCL connection is open-drain, the slave has the ability to hold that line low until it is ready to continue communicating.

Clock stretching allows receivers that cannot keep up with a transmitter to control the flow of incoming data.

## 25.3.2 ARBITRATION

Each master device must monitor the bus for Start and Stop bits. If the device detects that the bus is busy, it cannot begin a new message until the bus returns to an Idle state.

However, two master devices may try to initiate a transmission on or about the same time. When this occurs, the process of arbitration begins. Each transmitter checks the level of the SDA data line and compares it to the level that it expects to find. The first transmitter to observe that the two levels don't match, loses arbitration, and must stop transmitting on the SDA line.

For example, if one transmitter holds the SDA line to a logical one (lets it float) and a second transmitter holds it to a logical zero (pulls it low), the result is that the SDA line will be low. The first transmitter then observes that the level of the line is different than expected and concludes that another transmitter is communicating.

The first transmitter to notice this difference is the one that loses arbitration and must stop driving the SDA line. If this transmitter is also a master device, it also must stop driving the SCL line. It then can monitor the lines for a Stop condition before trying to reissue its transmission. In the meantime, the other device that has not noticed any difference between the expected and actual levels on the SDA line continues with its original transmission. It can do so without any complications, because so far, the transmission appears exactly as expected with no other transmitter disturbing the message. Slave Transmit mode can also be arbitrated, when a master addresses multiple slaves, but this is less common.

If two master devices are sending a message to two different slave devices at the address stage, the master sending the lower slave address always wins arbitration. When two master devices send messages to the same slave address, and addresses can sometimes refer to multiple slaves, the arbitration process must continue into the data stage.

Arbitration usually occurs very rarely, but it is a necessary process for proper multi-master support.

## 25.4 I<sup>2</sup>C Mode Operation

All MSSP1 I<sup>2</sup>C communication is byte oriented and shifted out MSb first. Six SFR registers and two interrupt flags interface the module with the PIC<sup>®</sup> microcontroller and user software. Two pins, SDA and SCL, are exercised by the module to communicate with other external I<sup>2</sup>C devices.

## 25.4.1 BYTE FORMAT

All communication in  $I^2C$  is done in 9-bit segments. A byte is sent from a Master to a Slave or vice-versa, followed by an Acknowledge bit sent back. After the 8th falling edge of the SCL line, the device outputting data on the SDA changes that pin to an input and reads in an acknowledge value on the next clock pulse.

The clock signal, SCL, is provided by the master. Data is valid to change while the SCL signal is low, and sampled on the rising edge of the clock. Changes on the SDA line while the SCL line is high define special conditions on the bus, explained below.

## 25.4.2 DEFINITION OF I<sup>2</sup>C TERMINOLOGY

There is language and terminology in the description of I<sup>2</sup>C communication that have definitions specific to I<sup>2</sup>C. That word usage is defined below and may be used in the rest of this document without explanation. This table was adapted from the Philips I<sup>2</sup>C<sup>TM</sup> specification.

## 25.4.3 SDA AND SCL PINS

Selection of any I<sup>2</sup>C mode with the SSP1EN bit set, forces the SCL and SDA pins to be open-drain. These pins should be set by the user to inputs by setting the appropriate TRIS bits.

**Note:** Data is tied to output zero when an I<sup>2</sup>C mode is enabled.



RETFIE	Return from Interrupt		
Syntax:	[label] RETFIE		
Operands:	None		
Operation:	$\begin{array}{l} TOS \to PC, \\ 1 \to GIE \end{array}$		
Status Affected:	None		
Description:	Return from Interrupt. Stack is POPed and Top-of-Stack (TOS) is loaded in the PC. Interrupts are enabled by setting Global Interrupt Enable bit, GIE (INTCON<7>). This is a 2-cycle instruction.		
Words:	1		
Cycles:	2		
Example:	RETFIE		
	After Interrupt PC = TOS GIE = 1		

RETURN	Return from Subroutine		
Syntax:	[label] RETURN		
Operands:	None		
Operation:	$TOS \rightarrow PC$		
Status Affected:	None		
Description:	Return from subroutine. The stack is POPed and the top of the stack (TOS) is loaded into the program counter. This is a 2-cycle instruction.		

RETLW	Return with literal in W		Pototo Loft f through Corry			
Syntax:	[ <i>label</i> ] RETLW k		Rotate Left I through Carry			
Operands:	$0 \le k \le 255$	Syntax:	[ <i>label</i> ] RLF f,d			
Operation:	$k \rightarrow (W);$ TOS $\rightarrow PC$	Operands:	$0 \le f \le 127$ $d \in [0,1]$			
Status Affected	None	Operation:	See description below			
Description:	cription: The W register is loaded with the 8-bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a 2-cycle instruction.	Status Affected: C				
Description.		Description:	The contents of register 'f' are rotated one bit to the left through the Carry flag. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is			
Words:	1		stored back in register T.			
Cycles:	2					
Example:	CALL TABLE;W contains table	Words:	1			
	<pre>;offset value , W now has table value</pre>	Cycles:	1			
TABLE	•	Example:	RLF REG1,0			
	<pre>• ADDWF PC ;W = offset RETLW k1 ;Begin table RETLW k2 ; • • • RETLW kn ; End of table Before instruction</pre>		Before Instruction       REG1       =       1110       0110         C       =       0           After Instruction       REG1       =       1110       0110         W       =       1100       1100          C       =       1			
	Before Instruction W = 0x07					
	After Instruction					
	W = value of k8					

RRF	Rotate Right f through Carry		
Syntax:	[ <i>label</i> ] RRF f,d		
Operands:	$\begin{array}{l} 0\leq f\leq 127\\ d\in [0,1] \end{array}$		
Operation:	See description below		
Status Affected:	С		
Description:	The contents of register 'f' are rotated one bit to the right through the Carry flag. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.		



SUBLW	Subtract W from literal		
Syntax:	[ <i>label</i> ] SUBLW k		
Operands:	$0 \leq k \leq 255$		
Operation:	$k - (W) \to (W)$		
Status Affected:	C, DC, Z		
Description:	The W register is subtracted (2's com- plement method) from the 8-bit literal 'k'. The result is placed in the W regis- ter.		
	C = 0 W > k		
	C = 1 W ≤ k		

DC = 0

DC = 1

W<3:0> > k<3:0>

 $W<3:0> \le k<3:0>$ 

SLEEP	Enter Sleep mode
Syntax:	[label] SLEEP
Operands:	None
Operation:	$\begin{array}{l} 00h \rightarrow WDT, \\ 0 \rightarrow \underline{WDT} \text{ prescaler}, \\ 1 \rightarrow \underline{TO}, \\ 0 \rightarrow \overline{PD} \end{array}$
Status Affected:	TO, PD
Description:	The power-down Status bit, $\overline{\text{PD}}$ is cleared. Time-out Status bit, $\overline{\text{TO}}$ is set. Watchdog Timer and its pres- caler are cleared. The processor is put into Sleep mode with the oscillator stopped.

SUBWF	Subtract W from f			
Syntax:	[label] SU	JBWF f,d		
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d  \in  [0,1] \end{array}$			
Operation:	(f) - (W) $\rightarrow$ (d	lestination)		
Status Affected:	C, DC, Z			
Description:	Subtract (2's complement method) W register from register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is ' $1$ ', the result is stored back in register 'f.			
	<b>C</b> = 0	W > f		
	<b>C =</b> 1	$W \leq f$		
	DC = 0	W<3:0> > f<3:0>		
	DC = 1	W<3:0> ≤ f<3:0>		

SUBWFB	Subtract W from f with Borrow	
Syntax:	SUBWFB f {,d}	
Operands:	$\begin{array}{l} 0\leq f\leq 127\\ d\in [0,1] \end{array}$	
Operation:	$(f) - (W) - (\overline{B}) \rightarrow dest$	
Status Affected:	C, DC, Z	
Description:	Subtract W and the BORROW flag (CARRY) from register 'f' (2's comple- ment method). If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored back in register 'f'.	



## 30.9 High Temperature Operation

This section outlines the specifications for the following devices operating in the high temperature range between  $-40^{\circ}$ C and  $150^{\circ}$ C.<sup>(2)</sup>

- PIC12F1822<sup>(4)</sup>
- PIC16F1823<sup>(4)</sup>

When the value of any parameter is identical for both the 125°C Extended and the 150°C High Temp. temperature ranges, then that value will be found in the standard specification tables shown earlier in this chapter, under the fields listed for the 125°C Extended temperature range. If the value of any parameter is unique to the 150°C High Temp. temperature range, then it will be listed here, in this section of the data sheet.

If a Silicon Errata exists for the product and it lists a modification to the 125°C Extended temperature range value, one that is also shared at the 150°C High Temp. temperature range, then that modified value will apply to both temperature ranges.

- Note 1: Writes are <u>not allowed</u> for Flash program memory above 125°C.
  - 2: AEC-Q100 reliability testing for devices intended to operate at 150°C is 1,000 hours. Any design in which the total operating time from 125°C to 150°C will be greater than 1,000 hours is not warranted without prior written approval from Microchip Technology Inc.
  - **3:** The temperature range indicator in the catalog part number and device marking is "H" for -40°C to 150°C.

Example: PIC12F1822T-H/SN indicates the device is shipped in a Tape and Reel configuration, in the SOIC package, and is rated for operation from -40°C to 150°C.

- 4: The low voltage versions of these devices, PIC12LF1822 and PIC16LF1823, is not released for operation above +125°C.
- Errata Sheet DS80502 lists various mask revisions. 150°C operation applies only to revisions A9 and later.
- 6: The Capacitive Sensing module (CPS) should not be used in High Temperature devices. Function and its parametrics are not warranted.
- Only SOIC (SN or SL), TSSOP (ST), and DFN/QFN (MF or ML) packages will be offered, not PDIP or UQFN.

Parameter	Condition	Value	
Max. Current: VDD	Source	15 mA	
Max. Current: Vss	Sink	15 mA	
Max. Current: Pin	Source	5 mA	
Max. Current: Pin	Sink	5 mA	
Max. Storage Temperature	—	-65°C to 155°C	
Max. Junction Temperature	—	+155°C	
Ambient Temperature under Bias	—	-40°C to +150°C	

## TABLE 30-18: ABSOLUTE MAXIMUM RATINGS

**Note:** Stresses above those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure above maximum rating conditions for extended periods may affect device reliability.

## 8-Lead Plastic Dual In-Line (P) - 300 mil Body [PDIP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging







	Units		INCHES	
Dimension Limits		MIN	NOM	MAX
Number of Pins N		8		
Pitch	е	.100 BSC		
Top to Seating Plane	Α	-	-	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	-	-
Shoulder to Shoulder Width	E	.290	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.348	.365	.400
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	С	.008	.010	.015
Upper Lead Width	b1	.040	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	-	-	.430

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. § Significant Characteristic
- 3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- 4. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-018D Sheet 2 of 2